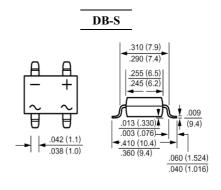


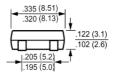
FEATURES

- · Glass passivated chip junction
- \cdot Low forward voltage drop
- \cdot High surge overload rating of 50 Amperes peak
- \cdot Ideal for printed circuit board
- High temperature soldering guaranteed: 260°C for 10 seconds

MECHANICAL DATA

Case: Molded plastic, DB-S Epoxy: UL 94V-O rate flame retardant Terminals: Leads solderable per MIL-STD-202, method 208 guaranteed Mounting position: Any Weight: 0.02ounce, 0.4gram





Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25 ambient temperature unless otherwise specified. Single phase, half wave, $60H_Z$, resistive or inductive load. For capacitive load, derate current by 20%.

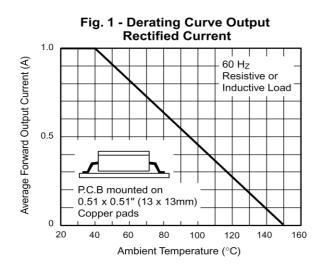
| | Symbols | DF005S | DF01S | DF02S | DF04S | DF06S | DF08S | DF10S | Units |
|---|-----------------------|---------------------|-------|-------|------------|-------|-------|-------|-------|
| Maximum Recurrent Peak Reverse Voltage | V _{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | Volts |
| Maximum RMS Voltage | V _{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | Volts |
| Maximum DC Blocking Voltage | V _{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | Volts |
| Maximum Average Forward Rectified Current at T _A =40 (Note 2) | I _(AV) | | | | 1.5 | • | | • | Amp |
| Peak Forward Surge Current, | | | | | | | | | |
| 8.3ms single half-sine-wave | I _{FSM} | I _{FSM} 50 | | | | | | | Amp |
| superimposed on rated load (JEDEC method) | | | | | | | | | |
| Maximum Forward Voltage at 1.0A DC and 25 | V _F | 1.1 | | | | | | | Volts |
| Maximum Reverse Current at T _A =25 | T | | | | 5.0 | | | | |
| at Rated DC Blocking Voltage T _A =125 | I _R | 500 | | | | | | | uAmp |
| Typical Junction Capacitance (Note 1) | CJ | 25 | | | | | | | pF |
| Typical Thermal Resistance (Note 2) | $R_{\theta JA}$ | 40 | | | | | | | /W |
| Typical Thermal Resistance (Note 2) | R _{0JL} | 15 | | | | | | | /W |
| Operating and Storage Temperature Range | T _J , Tstg | | | | -55 to +15 | 0 | | | |

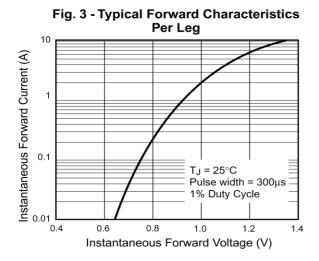
NOTES:

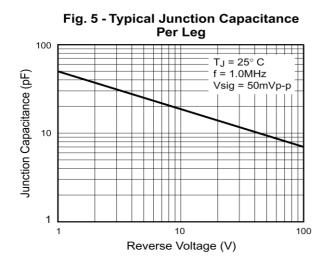
1- Measured at 1 MH_Z and applied reverse voltage of 4.0 VDC.

2- Units mounted on P.C.B. with 0.5 x 0.5" (13 x 13mm) copper pads









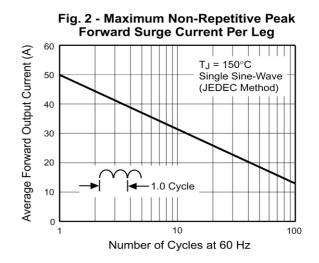


Fig. 4 - Typical Reverse Leakage Characteristics Per Leg

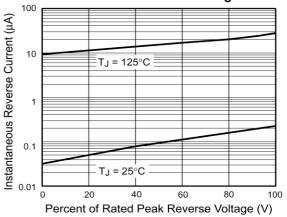


Fig. 6 - Typical Transient Thermal Impedance

